MOSEL VITELIC V62C51864 8K X 8 STATIC RAM

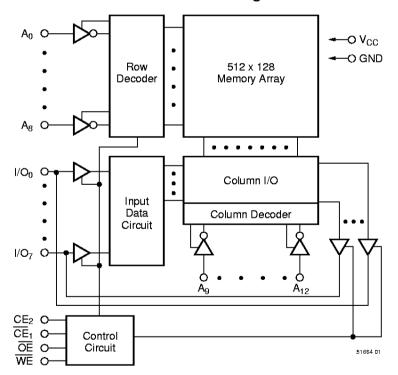
Features

- High-speed: 35, 70 ns
- Ultra low DC operating current of 5mA (max.)
- Low Power Dissipation:
 - TTL Standby: 2 mA (Max.)
 - CMOS Standby: 15 μA (Max.)
- Fully static operation
- All inputs and outputs directly compatible
- Three state outputs
- Ultra low data retention current (V_{CC} = 2V)
- Single 5V ± 10% Power Supply
- Packages
 - 28-pin 600 mil PDIP
 - 28-pin 330 mil SOP (450 mil pin-to-pin)

Description

The V62C51864 is a 65,536-bit static random access memory organized as 8,192 words by 8 bits. It is built with MOSEL VITELIC's high performance CMOS process. Inputs and three-state outputs are TTL compatible and allow for direct interfacing with common system bus structures.

Functional Block Diagram



Device Usage Chart

Operating	Package	Outline	Access Time (ns)		Pow	er	Town o wet	
Temperature Range	Р	F	35	70	L	LL	Temperature Mark	
0°C to 70°C	•	•	•	•	•	•	Blank	
-40°C to +85°C	•	•	•	•	•	•	1	

Pin Descriptions

A₀-A₁₂ Address Inputs

These 13 address inputs select one of the 8,192 x 8-bit words in the RAM.

CE₁, CE₂ Chip Enable Inputs

CE₁ is active LOW and CE₂ is active HIGH. Both chip enables must be active to read from or write to the device. If either chip enable is not active, the device is deselected and is in a standby power mode. The I/O pins will be in the high-impedance state when deselected.

OE Output Enable Input

The Output Enable input is active LOW. When \overline{OE} is LOW with \overline{CE}_1 LOW, CE_2 HIGH, and \overline{WE} HIGH, data of the selected memory location will be available on the I/O pins. When \overline{OE} is HIGH, the I/O pins will be in the high impedance state.

WE Write Enable Input

An active LOW input, \overline{WE} input controls read and write operations. When \overline{CE}_1 and \overline{WE} inputs are both LOW with CE_2 HIGH, the data present on the I/O pins will be written into the selected memory location.

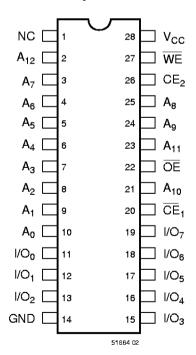
I/O₀-I/O₇ Data Input/Output Ports

These 8 bidirectional ports are used to read data from and write data into the RAM.

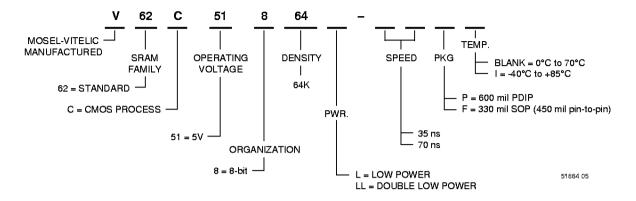
V_{CC} Power Supply

GND Ground

Pin Configuration 28-Pin Plastic DIP/SOP Top View



Part Number Information



Absolute Maximum Ratings (1)

Symbol	Parameter	Commercial	Industrial	Units
V _{CC}	Supply Voltage	-0.5 to +7	-0.5 to +7	٧
$\overline{V_N}$	Input Voltage	-0.5 to +7	-0.5 to +7	٧
V _{DQ}	Input/Output Voltage Applied	c\c + 0.5	V _{CC} + 0.5	٧
T _{BIAS}	Temperature Under Bias	-10 to +125	-65 to +135	°C
T _{STG}	Storage Temperature	-55 to +125	-65 to +150	°C

NOTE:

Capacitance*

 $T_A = 25$ °C, f = 1.0MHz

Symbol	Parameter	Conditions Max		Unit
CIN	Input Capacitance	/√ = 0Λ	6	рF
C _{OUT}	Output Capacitance	}⁄ _O = 0V	8	pF

NOTE:

Truth Table

Mode	Œ ₁	CE ₂	ŌĒ	WE	I/O Operation
Standby	Η	Х	Х	Х	High Z
Standby	Х	L	Х	Х	High Z
Output Disable	L	Н	Н	Н	High Z
Read	L	Н	L	Н	D _{OUT}
Write	L	Н	Х	L	D _{IN}

NOTE:

X = Don't Care, L = LOW, H = HIGH

^{1.} Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

^{*} This parameter is guaranteed and not tested.

DC Electrical Characteristics (over all temperature ranges, V_{CC} = 5V ± 10%)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
V _{IL}	Input LOW Voltag(2).2)		-0.5	_	0.8	٧
V _{IH}	Input HIGH Voltag년)		2.2	_	6	٧
I _{IL}	Input Leakage Current	$V_C = Max$, $V_{IN} = 0V$ to V_{CC}	-5	_	5	μΑ
l _{OL}	Output Leakage Current	$V_C = Max, \overline{CE} = V_{IH}, V_{OUT} = 0V \text{ to } V_{CC}$	-5	_	5	μΑ
V _{OL}	Output LOW Voltage	y _C = Min, l _{OL} = 2.1mA	_	_	0.4	V
V _{OH}	Output HIGH Voltage	&C = Min, IOH = -1mA	2.4	_	_	٧

Symbol	Parameter		Power	Com. ⁽⁴⁾	Ind. ⁽⁴⁾	Units
lcc				5	6	mA
	Output Open, $ ot\!$	WRITE		0	50	
l _{CC1}	Average Operating Current, $\overline{C} \not\models = V_{IL}$, $CE_2 = V_{IH}$, Output Open, $V_{CC} = Max.$, $f = f_{MAX}^{(3)}$			60	70	mA
I _{SB}	TTL Standby Current		L	3	4	mA
	$\overline{CE}_1 \ge V_{ H}, CE_2 \le V_{ L}, V_{CC} = Max.$		LL	2	3	
I _{SB1}			L	60	70	μА
	$V_{IN} \ge V_{CC} - 0.2V$ or $V_{N} \le 0.2V$, $V_{CC} = Max$.		LL	15	30	

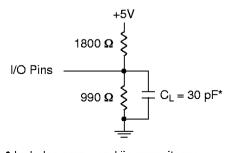
NOTES:

- These are absolute values with respect to device ground and all overshoots due to system or tester noise are included.
- $V_{\rm IL}$ (Min.) = -3.0V for pulse width < 20ns.
- f_{MAX} = 1/t_{RC}. Maximum values.

AC Test Conditions

Input Pulse Levels	0 to 3V
Input Rise and Fall Times	5 ns
Timing Reference Levels	1.5V
Output Load	see below

AC Test Loads and Waveforms



^{*} Includes scope and jig capacitance

51864 06

Key to Switching Waveforms

WAVEFORM	INPUTS	OUTPUTS
	MUST BE STEADY	WILL BE STEADY
	MAY CHANGE FROM H TO L	WILL BE CHANGING FROM H TO L
	MAY CHANGE FROM L TO H	WILL BE CHANGING FROM L TO H
	DON'T CARE: ANY CHANGE PERMITTED	CHANGING: STATE UNKNOWN
> «	DOES NOT APPLY	CENTER LINE IS HIGH IMPEDANCE "OFF" STATE

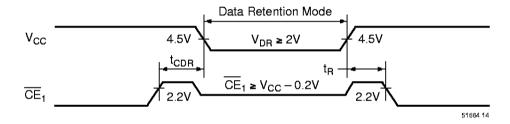
Data Retention Characteristics

Symbol	Parameter		Power	Min.	Typ. ⁽²⁾	Max.	Units
V_{DR}	V_{CC} for Data Retention $\overline{CF} \ge V_{CC} - 0.2V$, $CF_2 \le 0.2V$, $V_{IN} \ge V_{CC} - 0.2V$, or $V_{N} \le 0$.			2.0		5.5	٧
I _{CCDR}	$CE_1 \ge V_{DR} - 0.2V$, $CE_2 \le 0.2V$, $V_{IN} \ge V_{CC} - 0.2V$, or $V_{N} \le 0.2V$	Com'l	Г		0.5	50	μΑ
			LL		0.5	10	
		Ind.	L	_	_	70	
			LL	_	_	20	
t _{CDR}	Chip Deselect to Data Retention Time			0	_	_	ns
t _R	Operation Recovery Time (see Retention Waveform)			в ₺ ⁽¹⁾	_	_	ns

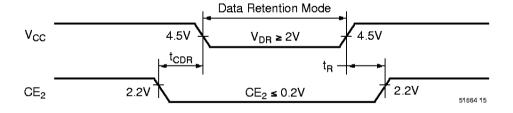
NOTES:

 t_{RC} = Read Cycle Time T_A = +25°C.

Low V_{CC} Data Retention Waveform (1) (CE₁ Controlled)



Low V_{CC} Data Retention Waveform (2) (CE₂ Controlled)



AC Electrical Characteristics

(over all temperature ranges)

Read Cycle

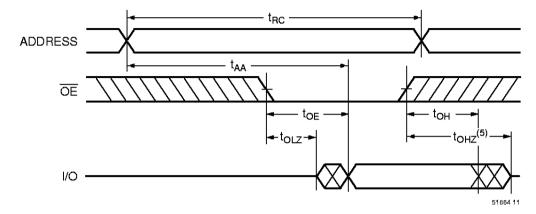
Parameter		-35		-7		
Name	Parameter	Min.	Max.	Min.	Max.	Unit
^t RC	Read Cycle Time	35	_	70	_	ns
t _{AA}	Address Access Time	_	35	_	70	ns
t _{ACS1}	Chip Enable Access Time	_	35	_	70	ns
t _{ACS2}	Chip Enable Access Time	_	35	_	70	ns
toE	Output Enable to Output Valid	_	15	_	30	ns
^t CLZ1	Chip Enable to Output in Low Z	5	_	5	_	ns
t _{CLZ2}	Chip Enable to Output in Low Z	5	_	5	_	ns
toLZ	Output Enable to Output in Low Z	5	_	5	_	ns
t _{CHZ}	Chip Disable to Output in High Z	0	20	0	20	ns
t _{OHZ}	Output Disable to Output in High Z	0	20	0	20	ns
tон	Output Hold from Address Change	5	_	5	_	ns

Write Cycle

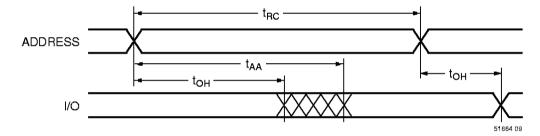
Parameter		-35		-70		
Name	Parameter	Min.	Max.	Min.	Max.	Unit
twc	Write Cycle Time	35	_	70	_	ns
tow	Chip Enable to End of Write	35	_	70	_	ns
t _{AS}	Address Setup Time	0	_	0	_	ns
t _{AW}	Address Valid to End of Write	35	_	70	_	ns
t _{WP}	Write Pulse Width	25	_	50	_	ns
twR	Write Recovery Time	0	_	0	_	ns
t _{WHZ}	Write to Output High-Z	0	20	0	25	ns
t _{DW}	Data Setup to End of Write	25	_	30		ns
t _{DH}	Data Hold from End of Write	0	_	0	_	ns
tow	Output Active from End of Write	5	_	5		ns

Switching Waveforms (Read Cycle)

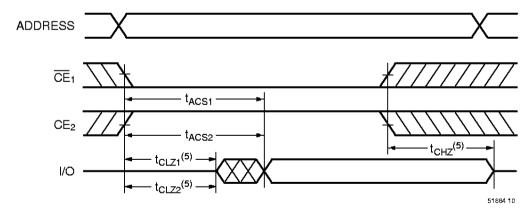
Read Cycle 1^(1, 2)



Read Cycle 2^(1, 2, 4)



Read Cycle 3^(1, 3, 4)

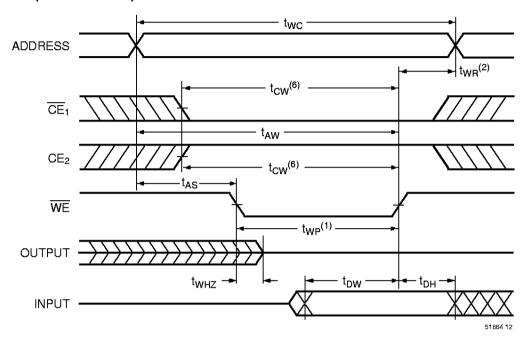


NOTES:

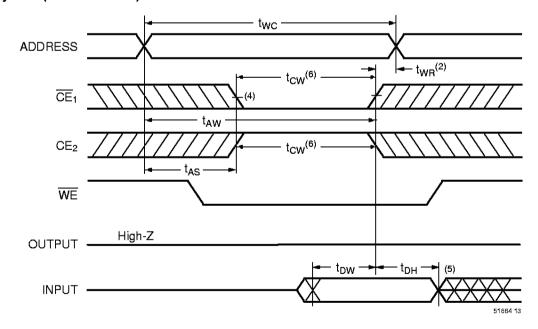
- 1.
- $\overline{WE} = V_{IH}$. $\overline{CE}_1 = V_{IL}$ and $\overline{CE}_2 = V_{IH}$.
- Address valid prior to or coincident with CE ransition LOW and/or CE transition HIGH.
- 4.
- Transition is measured 500mV from steady state with C = 5pF. This parameter is guaranteed and not 100% tested.

Switching Waveforms (Write Cycle)

Write Cycle 1 (WE Controlled)(4)



Write Cycle 2 (CE Controlled)(4)

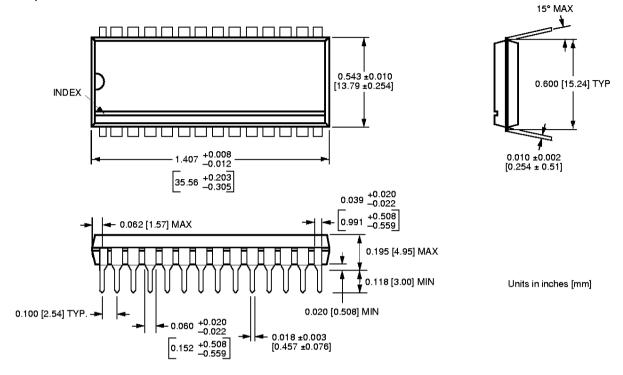


NOTES:

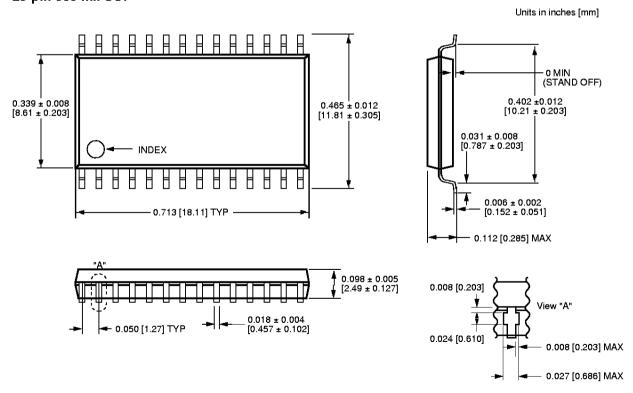
- 1. The internal write time of the memory is defined by the overlap of Attribute and Willow. Both signals must be active to initiate and any one signal can terminate a write by going inactive. The data input setup and hold timing should be referenced to the second transition edge of the signal that terminates the write.
- 2. two is measured from the earlier of CE or WE going HIGH, or CE going LOW at the end of the write cycle.
- 3. During this period, I/O pins are in the output state so that the input signals of opposite phase to the outputs must not be applied.
- 4. $\overline{OE} = V_{IL}$ or V_{IH} . However it is recommended to kee \overline{p} \overline{OE} t V_{IH} during write cycle to avoid bus contention.
- If CE₁ is LOW and CE₂ is HIGH during this period, I/O pins are in the output state. Then the data input signals of opposite phase
 to the outputs must not be applied to them.
- 6. tow is measured from CE going LOW or CE going HIGH to the end of write.

Package Diagrams

28-pin 600 mil Plastic DIP



28-pin 330 mil SOP



MOSEL VITELIC WORLDWIDE OFFICES

V62C51864

U.S.A.

3910 NORTH FIRST STREET SAN JOSE, CA 95134 PHONE: 408-433-6000 FAX: 408-433-0185

HONG KONG

19 DAI FU STREET TAIPO INDUSTRIAL ESTATE TAIPO, NT, HONG KONG PHONE: 852-2665-4883 FAX: 852-2664-7535

TAIWAN

7F, NO. 102 MIN-CHUAN E. ROAD, SEC. 3 TAIPEI

PHONE: 886-2-2545-1213 FAX: 886-2-2545-1209

1 CREATION ROAD I SCIENCE BASED IND. PARK HSIN CHU, TAIWAN, R.O.C. PHONE: 886-3-578-3344 FAX: 886-3-579-2838

JAPAN

WBG MARINE WEST 25F 6, NAKASE 2-CHOME MIHAMA-KU, CHIBA-SHI CHIBA 261-71

PHONE: 81-43-299-6000 FAX: 81-43-299-6555

IRELAND & UK

BLOCK A UNIT 2 BROOMFIELD BUSINESS PARK MALAHIDE

CO. DUBLIN, IRELAND PHONE: +353 1 8038020 FAX: +353 1 8038049

GERMANY (CONTINENTAL EUROPE & ISRAEL)

71083 HERRENBERG BENZSTR. 32 GERMANY

PHONE: +49 7032 2796-0 FAX: +49 7032 2796 22

U.S. SALES OFFICES

NORTHWESTERN

3910 NORTH FIRST STREET SAN JOSE, CA 95134 PHONE: 408-433-6000 FAX: 408-433-0185

NORTHEASTERN

SUITE 436 20 TRAFALGAR SQUARE NASHUA, NH 03063 PHONE: 603-889-4393 FAX: 603-889-9347

SOUTHWESTERN

SUITE 200 5150 E. PACIFIC COAST HWY. LONG BEACH, CA 90804 PHONE: 562-498-3314 FAX: 562-597-2174

CENTRAL & SOUTHEASTERN

604 FIELDWOOD CIRCLE RICHARDSON, TX 75081 PHONE: 972-690-1402 FAX: 972-690-0341

© Copyright 1998, MOSEL VITELIC Inc.

6/98 Printed in U.S.A.

The information in this document is subject to change without notice

MOSEL VITELIC makes no commitment to update or keep current the information contained in this document. No part of this document may be copied or reproduced in any form or by any means without the prior written consent of MOSEL-VITELIC.

MOSEL VITELIC subjects its products to normal quality control sampling techniques which are intended to provide an assurance of high quality products suitable for usual commercial applications. MOSEL VITELIC does not do testing appropriate to provide 100% product quality assurance and does not assume any liability for consequential or incidental arising from any use of its products. If such products are to be used in applications in which personal injury might occur from failure, purchaser must do its own quality assurance testing appropriate to such applications.